

PRINTED WIRING BOARD AND
METHOD OF MANUFACTURING SAME

Abstract of the Disclosure

A printed wiring board has a via land, a glass epoxy resin layer, a via conductor, and a block layer. The via land is formed on a core layer. The glass epoxy resin layer is formed on the core layer and the via land. The via conductor is formed on the via land. The block layer is formed on the via land, between the via conductor and the glass epoxy resin layer.